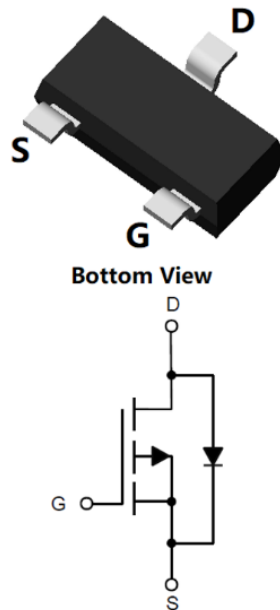
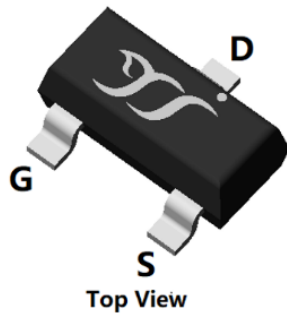


P-Channel Enhancement Mode Field Effect Transistor



SOT-23

Product Summary

• V_{DS}	-20V
• I_D	-3.4A
• $R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	<51mohm
• $R_{DS(ON)}$ (at $V_{GS}=-2.5V$)	<67mohm
• $R_{DS(ON)}$ (at $V_{GS}=-1.8V$)	<100mohm

General Description

- Trench Power LV MOSFET technology
- High Power and Current handling capability
- Low Gate Charge
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- PWM applications
- Power management
- Load switch

■ Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	-20	V
Gate-source Voltage		V_{GS}	± 10	V
Drain Current	$T_A=25^{\circ}C$	I_D	-3.4	A
	$T_A=70^{\circ}C$		-2.7	
Pulsed Drain Current ^A		I_{DM}	-14	A
Total Power Dissipation	$T_A=25^{\circ}C$	P_D	1	W
	$T_A=70^{\circ}C$		0.64	
Thermal Resistance Junction-to-Ambient ^B		$R_{\theta JA}$	125	$^{\circ}C/W$
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^{\circ}C$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJL2301C	F2	S1.	3000	30000	120000	7" reel



YJL2301C

■ Electrical Characteristics (T_J=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V,V _{GS} =0V			-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =-250μA	-0.4	-0.62	-1.0	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-3.4A		42	51	mΩ
		V _{GS} =-2.5V, I _D =-3.0A		55	67	
		V _{GS} =-1.8V, I _D =-2.5A		86	100	
Diode Forward Voltage	V _{SD}	I _S =-3.4A,V _{GS} =0V			-1.2	V
Maximum Body-Diode Continuous Current	I _S				-3.4	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =-10V,V _{GS} =0V,f=1MHz		438		pF
Output Capacitance	C _{oss}			76		
Reverse Transfer Capacitance	C _{rss}			62		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =-4.5V,V _{DS} =-10V,I _D =-3.4A		5.41		nC
Gate-Source Charge	Q _{gs}			1.17		
Gate-Drain Charge	Q _{gd}			1.24		
Reverse Recovery Chrage	Q _{rr}	I _F =-3.4A, di/dt=100A/us		4		ns
Reverse Recovery Time	t _{rr}			24.5		
Turn-on Delay Time	t _{D(on)}	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-1A R _{GEN} =3Ω		6.4		
Turn-on Rise Time	t _r			21.8		
Turn-off Delay Time	t _{D(off)}			37.4		
Turn-off fall Time	t _f			34		

A. Pulse Test: Pulse Width≤300us, Duty cycle ≤2%.

B. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design, while R_{θJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



■ Typical Performance Characteristics

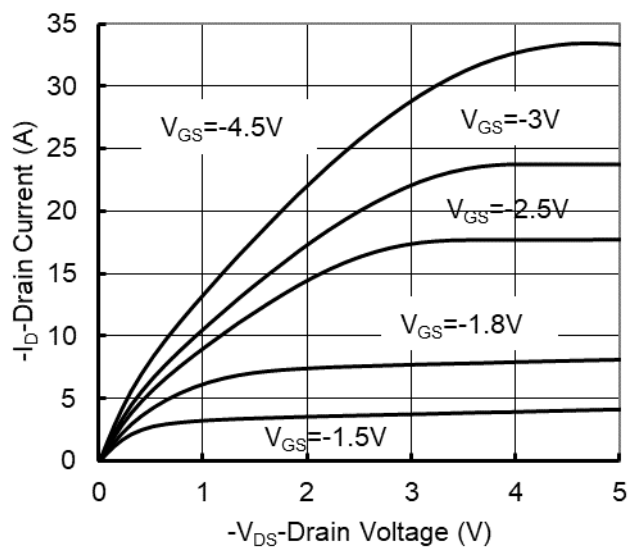


Figure1. Output Characteristics

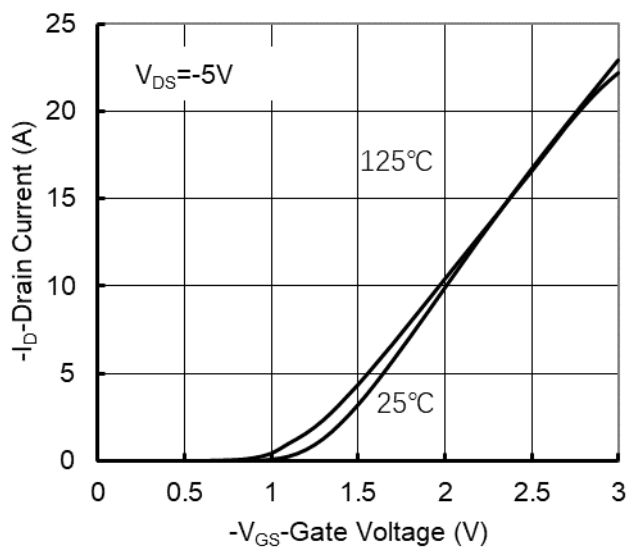


Figure2. Transfer Characteristics

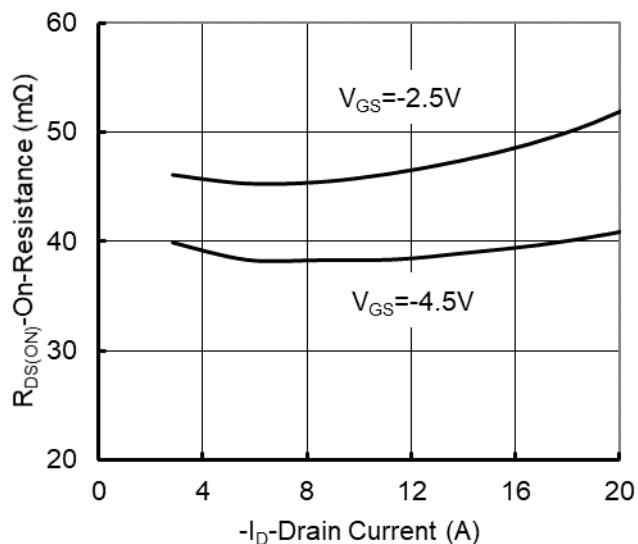


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

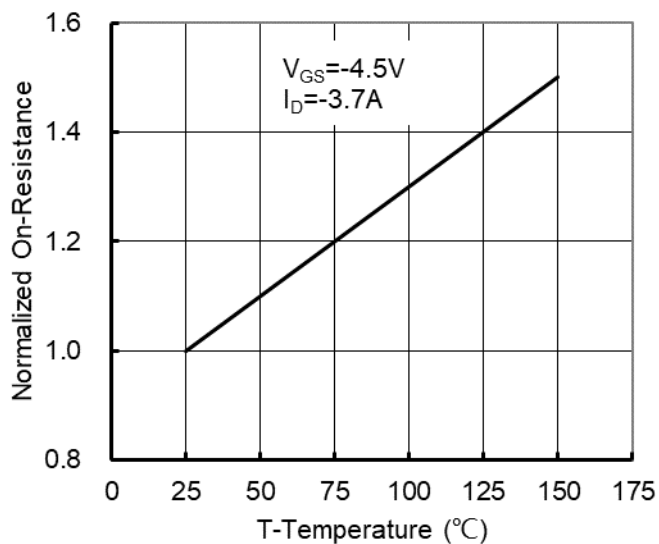


Figure 4: On-Resistance vs. Junction Temperature

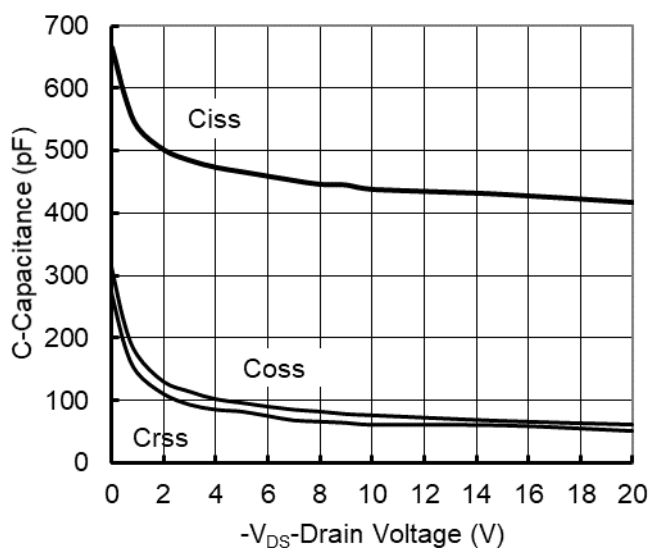


Figure5. Capacitance Characteristics

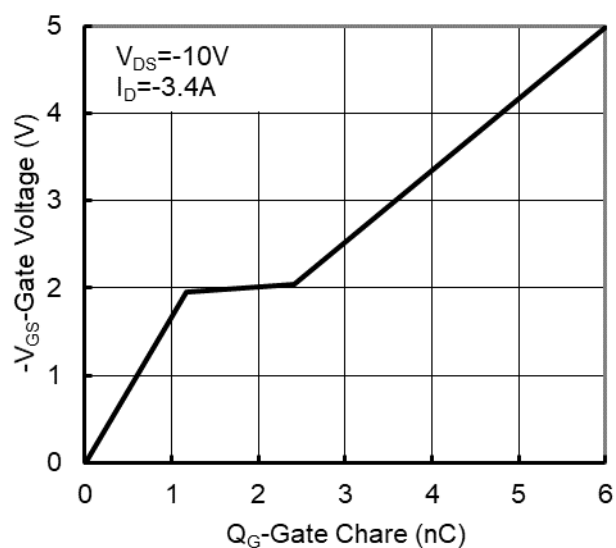
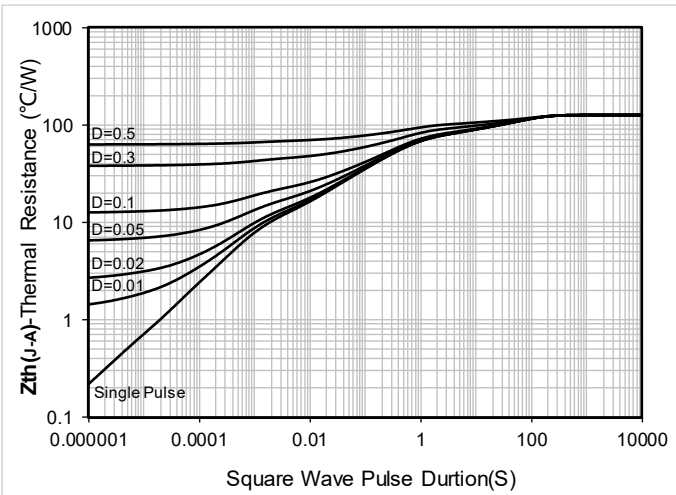
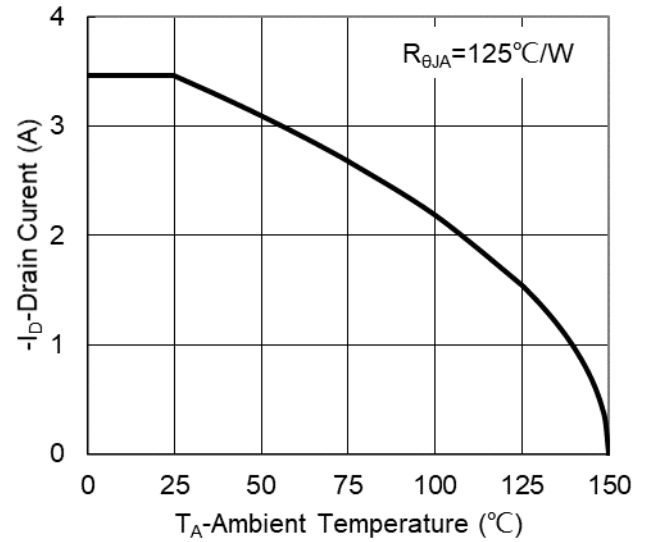
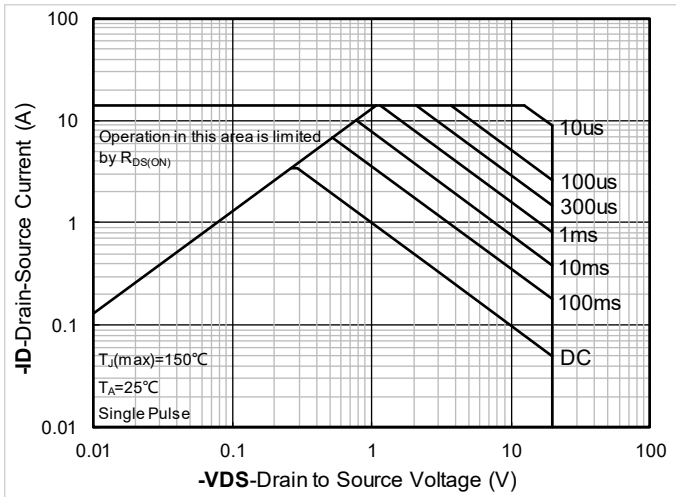
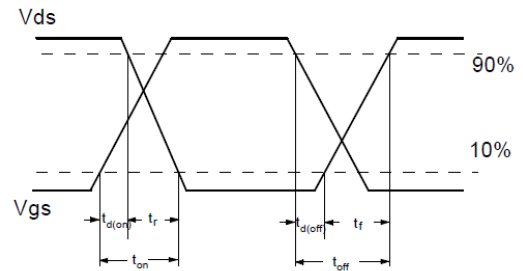
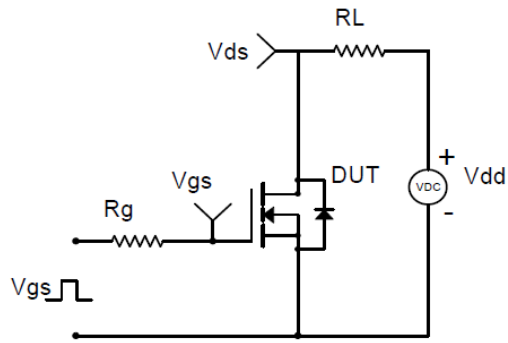
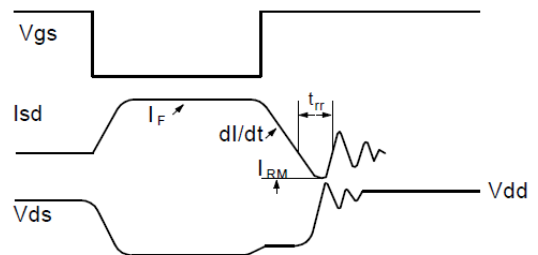
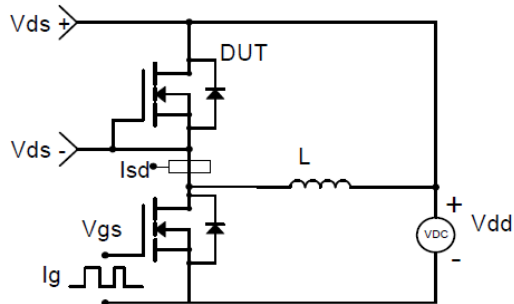


Figure6. Gate Charge

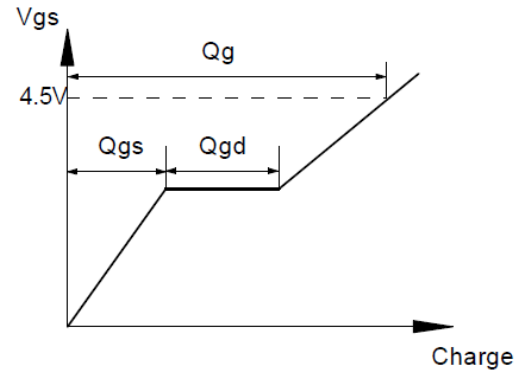
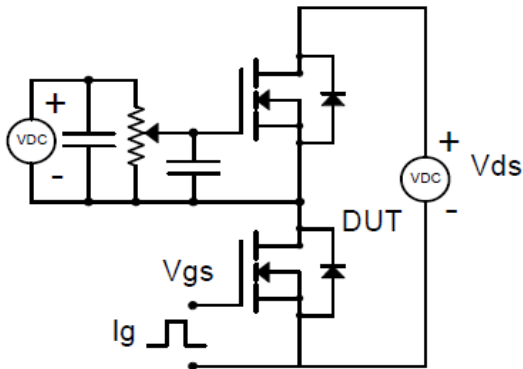




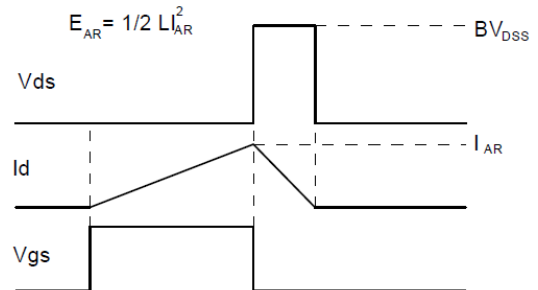
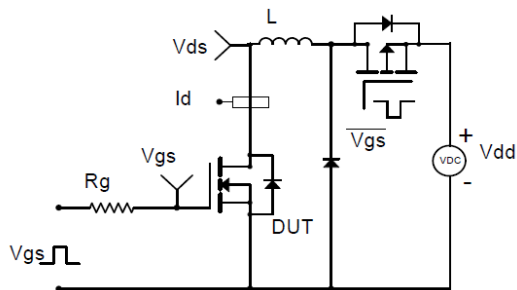
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Gate Charge Test Circuit & Waveform

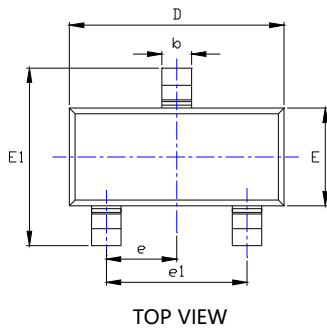


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

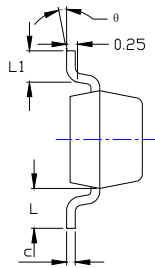


YJL2301C

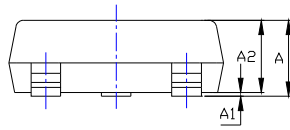
■ SOT-23 Package information



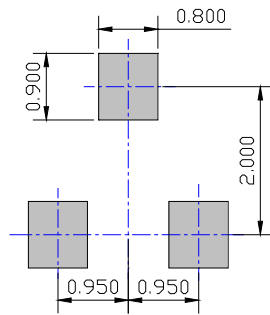
TOP VIEW



SIDE VIEW



SIDE VIEW



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT

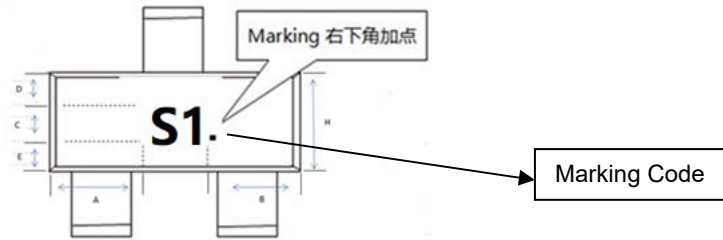
SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.045	0.900	1.150
A1	0.000	0.004	0.000	0.100
A2	0.035	0.041	0.900	1.050
b	0.012	0.020	0.300	0.500
c	0.004	0.008	0.100	0.200
D	0.110	0.118	2.800	3.000
E	0.047	0.055	1.200	1.400
E1	0.089	0.100	2.250	2.550
e	0.037TYP		0.950TYP	
e1	0.071	0.079	1.800	2.000
L	0.022REF		0.550REF	
L1	0.012	0.020	0.300	0.500
θ	0°	8°	0°	8°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



■ Marking Information



Note:

1. All marking is at middle of the product body
2. All marking is in laser printing
3. S1. is marking code
4. Body color: Black



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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

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